



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Heinen, et al.

Serial No.: 09/186,973

Filed: 11/05/98

For: Wafer-scale Assembly of Chip-size Packages

Docket No.: TI-23158

Examiner: Foong, S.

Art Unit: 2823

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Amendment under 37 CFR 1.111

Commissioner of Patents

P.O. Box 1450

Alexandria, VA, 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 7-14-03

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 3/14/03. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time accompanies this response. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.